

**REMARKS**

This is in response to the Office Action dated September 23, 2004. Non-elected claims 16-25 have been canceled, in view of the Restriction Requirement. Claims 14-15 have also been canceled. Claims 1-13 are pending.

With respect to the Restriction Requirement, Applicant has not suggested that withdrawn claims 16-25 are obvious over claims 1-15. This has not been stated or suggested by Applicant. In this respect, non-elected claims 16-25 have been canceled without prejudice in view of the Restriction Requirement.

The title has been amended as suggested by the Examiner.

Applicant notes with appreciation the Examiner's indication that claims 4-6 and 14 contain allowable subject matter. In this respect, allowable claim 4 has essentially been rewritten in independent form, and subject matter of allowable claim 14 has been added to claim 13. Thus, given the Examiner's indication of allowable subject matter, claims 4-6 and 13 are now in condition for allowance.

Claim 1 stands rejected as being allegedly anticipated by Knecht. This Section 102(b) rejection is respectfully traversed for at least the following reasons.

Claim 1 as amended requires "a flexible semiconductor chip including an element forming region where a semiconductor element is formed and an element non-forming region where a semiconductor element is not formed, each of the element forming region and the element non-forming region being provided on a front surface of a silicon substrate, a groove formed in a portion of a rear surface of said silicon substrate corresponding to said element non-forming region, wherein said groove does not extend all the way through the silicon substrate, so that the semiconductor chip is flexible."

Knecht fails to disclose or suggest the aforesaid underlined aspects of amended claim 1.

In particular, Knecht fails to disclose or suggest a flexible semiconductor chip. Moreover, Knecht fails to disclose or suggest that the "groove does not extend all the way through the silicon substrate, so that the semiconductor chip is flexible" as required by amended claim 1. The diaphragm of Knecht is not a chip, and does not represent a flexible semiconductor chip as called for in amended claim 1.

Claim 1 also stands rejected under 35 U.S.C. Section 102(b) as being allegedly anticipated by Willis. This Section 102(b) rejection is also respectfully traversed for at least the following reasons. In Willis, groove 503 is *not* formed in the semiconductor substrate 501 as required by claim 1 - instead, Willis' groove is formed in conductor 580 as discussed at col. 9, lines 1-25. Thus, Willis fails to disclose or suggest that the "groove does not extend all the way through the silicon substrate, so that the semiconductor chip is flexible" as required by amended claim 1.

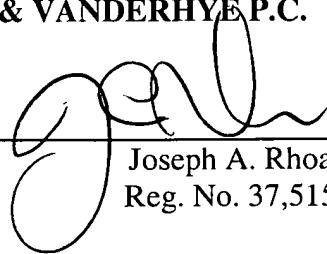
Claim 1 also stands rejected under Section 102(b) over Silverbrook. This Section 102(b) rejection is respectfully traversed for at least the following reasons. Silverbrook fails to disclose or suggest that the "*groove does not extend all the way through the silicon substrate*, so that the semiconductor *chip is flexible*" as required by amended claim 1. Instead, Silverbrook teaches directly away from this.

For at least the foregoing reasons, it is respectfully requested that all rejections be withdrawn. All claims are in condition for allowance. If any minor matter remains to be resolved, the Examiner is invited to telephone the undersigned with regard to the same.

OHARA  
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Respectfully submitted,

**NIXON & VANDERHYE P.C.**

By: 

Joseph A. Rhoa  
Reg. No. 37,515

JAR:caj  
1100 North Glebe Road, 8th Floor  
Arlington, VA 22201-4714  
Telephone: (703) 816-4000  
Facsimile: (703) 816-4100